



NOTES:

- CAMBER : 0.05 mm MAX.
- PLATING THICKNESS:  
ELECTRO Ni : 1.27 ~ 8.89 MICRON. (SOLDER PADS.)  
ELECTRO Au : 0.30 ~ 1.00 MICRON. (SOLDER PADS.)  
OTHERS : 0.30 MICRON MIN.
- CONNECTION:  
(A-C), (B-D), (B-2-S/R-D/A), (F-3), (G-4), (H-1)
- METALLIZATION RUNDOWN 0.20 MAX.
- EXPOSURE OF CERAMIC SURFACE AND METALLIZED PATTERN OCCURRED BY MISALIGNMENT OF THE UPPER LAYER, SHALL BE ALLOWED.
- PART TO BE SHOWN AS SIDE METALLIZED PATTERN.
- SEALING METHOD OF THIS PRODUCT SHALL BE SBAM WELD.
- STRESS RELAXATION DESIGN SHALL BE APPLIED ON THIS ITEM.

TOLERANCE	REVISION	SBB ATTACHED EXCEPTIONS SHEET.				TITLE
±1% N.L.T.±0.13 ANGLES	SCALE	DIMENSION	PROJECTION	CUSTOMER DWG NO.	REV.	5032 OSC PKG B
	20 : 1	mm	3rd			PART NO. S5032CLK4
MATERIAL	APPROVED	CHECKED	ENGRG	CHECKED	DESIGNED	REV. 0
90%MIN.A1203 (NA-311B BLACK)	Shigetomi	Yamahata	Ohba	Ano	Sakima	DWG NO. SHT/OF 1/6
	Nov.26.02	Nov.26.02	Nov.26.02	Nov.26.02	Nov.26.02	